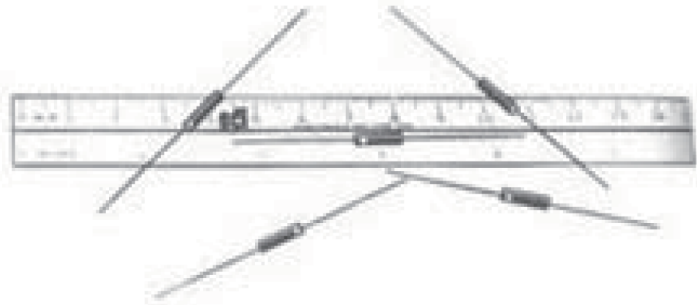




# DL 300 DL 1500

## FAST RECOVERY HIGH VOLTAGE 25mA MINIATURE SILICON RECTIFIERS

- SMALL SIZE MOLDED PACKAGE
- PRV 3,000 TO 15,000VOLTS
- 1.0 INCH MIN. LEADS
- LOW LEAKAGE



EDI Type	PRV Volts
DL300	3,000
DL500	5,000
DL800	8,000
DL1000	10,000
DL1200	12,000
DL1500	15,000

### ELECTRICAL CHARACTERISTICS (at $T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Average Rectified Forward Current @ $50^\circ\text{C}$ , $I_o$	25 mA
Max. Peak Surge Current, $I_{FSM}$ (8.3ms)	3 Amp
Max. Reverse Recovery $T_{rr}$ (Fig.4)	150nanosec
Max. Forward Voltage Drop @ 25 mA, $V_F$	26Volts
Max. DC Reverse Current @ PRV and $25^\circ\text{C}$ , $I_R$	1 $\mu\text{A}$
Max. DC Reverse Current @ PRV and $100^\circ\text{C}$ , $I_R$	25 $\mu\text{A}$
Ambient Operating Temperature Range, $T_A$	$-55^\circ\text{C}$ to $+125^\circ\text{C}$
Storage Temperature Range, $T_{STG}$	$-55^\circ\text{C}$ to $+150^\circ\text{C}$

#### NOTES:

1.It is recommended that a proper heat sink be used on the terminals of this device between the body and soldering point to prevent damage from excess heat.

2.If operated over 10,000v/inch in length, devices should be immersed in oil or ree - ncapsulated.

EDI reserves the right to change these specifications at any time without notice.

FIG.1

OUTPUT CURRENT vs AMBIENT TEMPERATURE

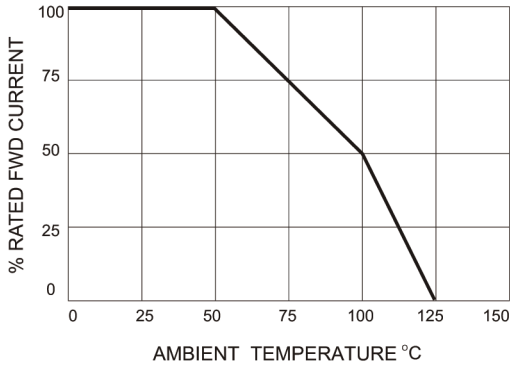


FIG.2

NON-REPETITIVE SURGE CURRENT

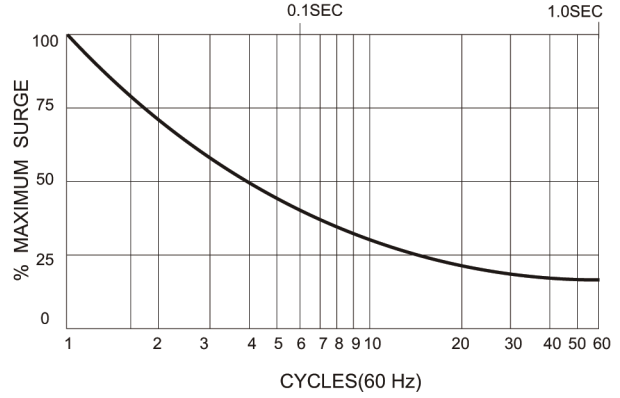


FIG.3  
MECHANICAL

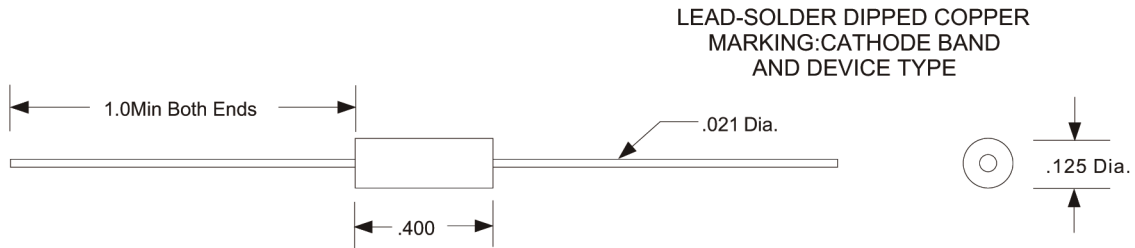
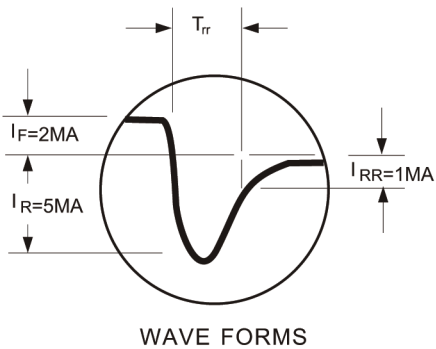


FIG.4  
REVERSE RECOVERY TEST METHOD

RECOVERY WAVE FORM



RECOVERY WAVE FORM

